

Title (en)

SELF-SUPPORTING CONTACTING STRUCTURES THAT ARE DIRECTLY PRODUCED ON COMPONENTS WITHOUT HOUSINGS

Title (de)

DIREKT AUF UNGEHÄUSTEN BAUELEMENTEN ERZEUGTE FREITRAGENDE KONTAKTIERSTRUKTUREN

Title (fr)

STRUCTURES DE MISE EN CONTACT AUTOPORTANTES PRODUITES DIRECTEMENT SUR DES COMPOSANTS SANS BOITIER

Publication

**EP 1597755 A2 20051123 (DE)**

Application

**EP 04702322 A 20040115**

Priority

- EP 2004000263 W 20040115
- DE 10308928 A 20030228

Abstract (en)

[origin: WO2004077546A2] A self-supporting contacting structure is directly produced on a component that does not have a housing by applying a layer made of nonconducting material and a layer made of an electrically conductive material to the component and to a support and by subsequently removing these layers from said support.

IPC 1-7

**H01L 21/60**; **H01L 21/68**

IPC 8 full level

**H01L 21/60** (2006.01); **H01L 21/56** (2006.01); **H01L 21/68** (2006.01); **H01L 23/48** (2006.01); **H01L 23/482** (2006.01)

CPC (source: EP KR US)

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Citation (search report)

See references of WO 2004077546A2

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